

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of

KONISHI et al.

Atty. Ref.: 829-615; Confirmation No.

Appl. No. To be Assigned

Group:

Filed: September 11, 2003

Examiner:

For: RESIN MOLDING DIE AND PRODUCTION METHOD FOR  
SEMICONDUCTOR DEVICES USING THE SAME

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September 11, 2003

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

**PRELIMINARY AMENDMENT**

In order to place the above-identified application in better condition for  
examination, please amend the application as follows: